

特征 Features

- 平面工艺芯片结构 Planar Die Construction
- 功耗100毫瓦 100mW Power Dissipation
- 稳压值范围从2.4到75V Zener Voltages From 2.4 – 75V

机械数据 Mechanical Data

- 封装: SOD-523 封装 SOD-523 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 环氧树脂UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25℃ 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25℃ ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value	单位 Unit
正向电压 Forward Voltage @IF=10mA	V _F	0.9	V
功率消耗 Power Dissipation (Note 1)	P _d	100	mW
结温 Junction temperature	T _j	-65-+150	℃
存储温度 Storage temperature range	T _{STG}	-65-+150	℃

电特性 **Electrical Characteristics** (Ratings at 25℃ ambient temperature unless otherwise specified.)

Device	Device Marking	Zener Voltage (Note 1)				Zener Impedance			Leakage Current		©V _Z (mV/k) @ I _{ZT}		C @ V _R = 0 f = 1 MHz
		V _Z (Volts)			@ I _{ZT}	Z _{ZT} @ I _{ZT}	Z _{ZK} @ I _{ZK}	I _R @ V _R					
		Min	Nom	Max	mA	fi	fi	mA	µA	Volts	Min	Max	pF
MM5Z2V4	00	2.2	2.4	2.6	5	100	1000	1.0	50	1.0	-3.5	0	450
MM5Z2V7	01	2.5	2.7	2.9	5	100	1000	1.0	20	1.0	-3.5	0	450
MM5Z3V0	02	2.8	3.0	3.2	5	100	1000	1.0	10	1.0	-3.5	0	450
MM5Z3V3	05	3.1	3.3	3.5	5	95	1000	1.0	5	1.0	-3.5	0	450
MM5Z3V6	06	3.4	3.6	3.8	5	90	1000	1.0	5	1.0	-3.5	0	450
MM5Z3V9	07	3.7	3.9	4.1	5	90	1000	1.0	3	1.0	-3.5	-2.5	450
MM5Z4V3	08	4.0	4.3	4.6	5	90	1000	1.0	3	1.0	-3.5	0	450
MM5Z4V7	09	4.4	4.7	5.0	5	80	800	1.0	3	2.0	-3.5	0.2	260
MM5Z5V1	0A	4.8	5.1	5.4	5	60	500	1.0	2	2.0	-2.7	1.2	225
MM5Z5V6	0C	5.2	5.6	6.0	5	40	200	1.0	1	2.0	-2.0	2.5	200
MM5Z6V2	0E	5.8	6.2	6.6	5	10	100	1.0	3	4.0	0.4	3.7	185
MM5Z6V8	0F	6.4	6.8	7.2	5	15	160	1.0	2	4.0	1.2	4.5	155
MM5Z7V5	0G	7.0	7.5	7.9	5	15	160	1.0	1	5.0	2.5	5.3	140
MM5Z8V2	0H	7.7	8.2	8.7	5	15	160	1.0	0.7	5.0	3.2	6.2	135
MM5Z9V1	0K	8.5	9.1	9.6	5	15	160	1.0	0.2	7.0	3.8	7.0	130
MM5Z10	0L	9.4	10	10.6	5	20	160	1.0	0.1	8.0	4.5	8.0	130
MM5Z11	0M	10.4	11	11.6	5	20	160	1.0	0.1	8.0	5.4	9.0	130
MM5Z12	0N	11.4	12	12.7	5	25	80	1.0	0.1	8.0	6.0	10	130
MM5Z13	0P	12.4	13.25	14.1	5	30	80	1.0	0.1	8.0	7.0	11	120
MM5Z15	0T	14.3	15	15.8	5	30	80	1.0	0.05	10.5	9.2	13	110
MM5Z16	0U	15.3	16.2	17.1	2	40	80	1.0	0.05	11.2	10.4	14	105
MM5Z18	0W	16.8	18	19.1	2	45	80	1.0	0.05	12.6	12.4	16	100
MM5Z20	0Z	18.8	20	21.2	2	55	100	1.0	0.05	14.0	14.4	18	85
MM5Z22	10	20.8	22	23.3	2	55	100	1.0	0.05	15.4	16.4	20	85
MM5Z24	11	22.8	24.2	25.6	2	70	120	1.0	0.05	16.8	18.4	22	80
MM5Z27	12	25.1	27	28.9	2	80	300	1.0	0.05	18.9	21.4	25.3	70
MM5Z30	14	28	30	32	2	80	300	1.0	0.05	21.0	24.4	29.4	70
MM5Z33	18	31	33	35	2	80	300	1.0	0.05	23.2	27.4	33.4	70
MM5Z36	19	34	36	38	2	90	500	1.0	0.05	25.2	30.4	37.4	70

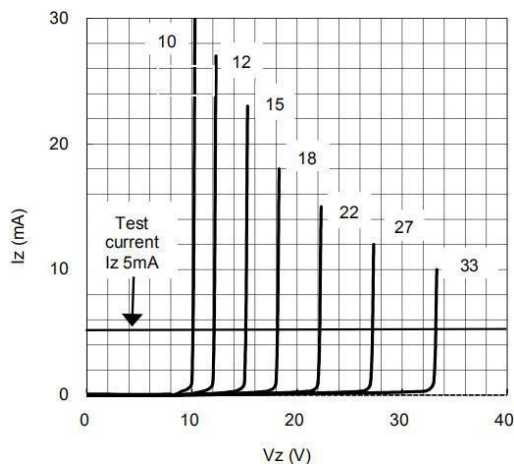
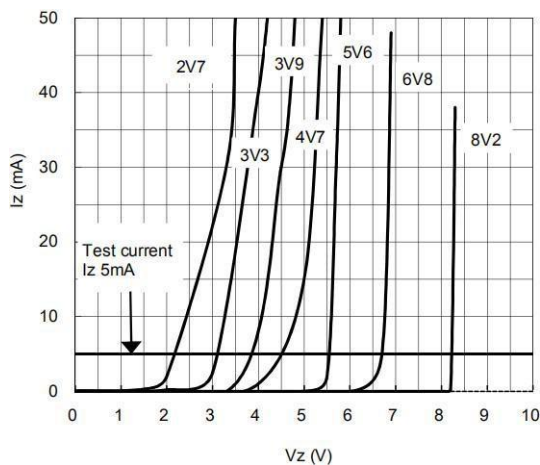
MM5Z39	20	37	39	41	2	130	500	1.0	0.05	27.3	33.4	41.2	45
MM5Z43	21	40	43	46	1	150	500	1.0	0.05	30.1	37.6	46.6	40
MM5Z47	1A	44	47	50	1	170	500	1.0	0.05	32.9	42.0	51.8	40
MM5Z51	1C	48	51	54	1	180	500	1.0	0.05	35.7	46.6	57.2	40
MM5Z56	1D	52	56	60	1	200	500	1.0	0.05	39.2	52.2	63.8	40
MM5Z62	1E	58	62	66	1	215	500	1.0	0.05	43.4	58.8	71.6	35
MM5Z68	1F	64	68	72	1	240	500	1.0	0.05	47.6	65.6	79.8	35
MM5Z75	1G	70	75	79	1	255	500	1.0	0.05	52.5	73.4	88.6	35

Notes:

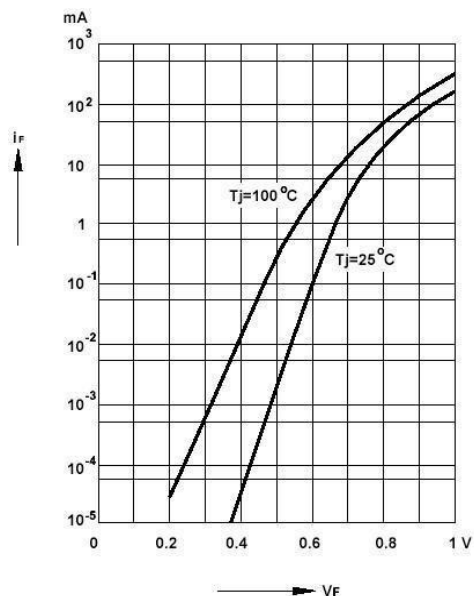
1. Valid provided that device terminals are kept at ambient temperature.

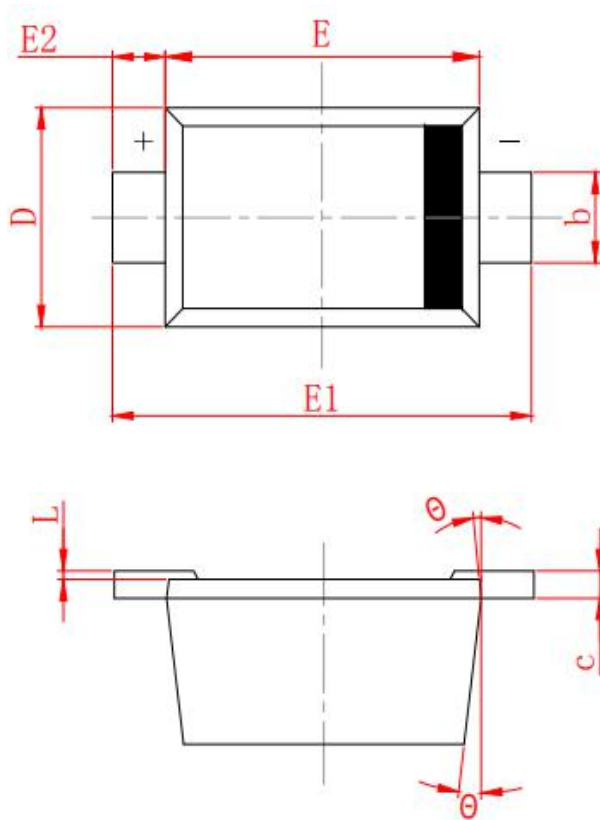
典型特性 Typical Characteristics

Breakdown characteristics
at $T_j = \text{constant}$ (pulsed)

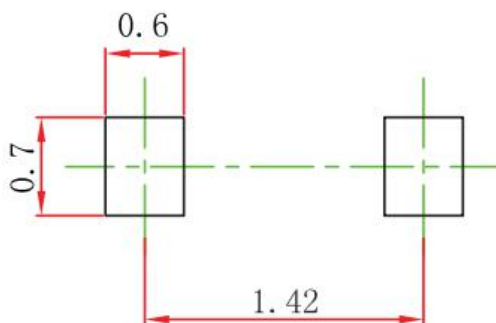


Forward characteristics



SOD-523封装外形尺寸图 SOD-523 Package Outline Dimensions


SYMBOL	MILLIMETER	
	MIN	MAX
A	0.530	0.730
A1	0.500	0.700
b	0.280	0.380
c	0.080	0.150
D	0.750	0.850
E	1.100	1.300
E1	1.500	1.700
E2	0.200 REF	
L	0.010	0.070
θ	7° REF	

SOD-523焊盘设计参考 SOD-523 Suggested Pad Layout


Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

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